AMD Xilinx - XC2VP2-6FGG256I Datasheet

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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	352
Number of Logic Elements/Cells	3168
Total RAM Bits	221184
Number of I/O	140
Number of Gates	-
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	256-BGA
Supplier Device Package	256-FBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xc2vp2-6fgg256i

ing character, and remembers its location in the buffer. At some point, one transceiver designated as the master instructs all the transceivers to align to the channel bonding character "P" (or to some location relative to the channel bonding character).

After this operation, words transmitted to the FPGA fabric are properly aligned: RRRR, SSSS, TTTT, and so forth, as shown in the bottom-right portion of Figure 7. To ensure that the channels remain properly aligned following the channel bonding operation, the master transceiver must also control the clock correction operations described in the previous section for all channel-bonded transceivers.

Transmitter Buffer

The transmitter's buffer write pointer (TXUSRCLK) is frequency-locked to its read pointer (REFCLK). Therefore, clock correction and channel bonding are not required. The purpose of the transmitter's buffer is to accommodate a phase difference between TXUSRCLK and REFCLK. A simple FIFO suffices for this purpose. A FIFO depth of four will permit reliable operation with simple detection of overflow or underflow, which could occur if the clocks are not frequency-locked.

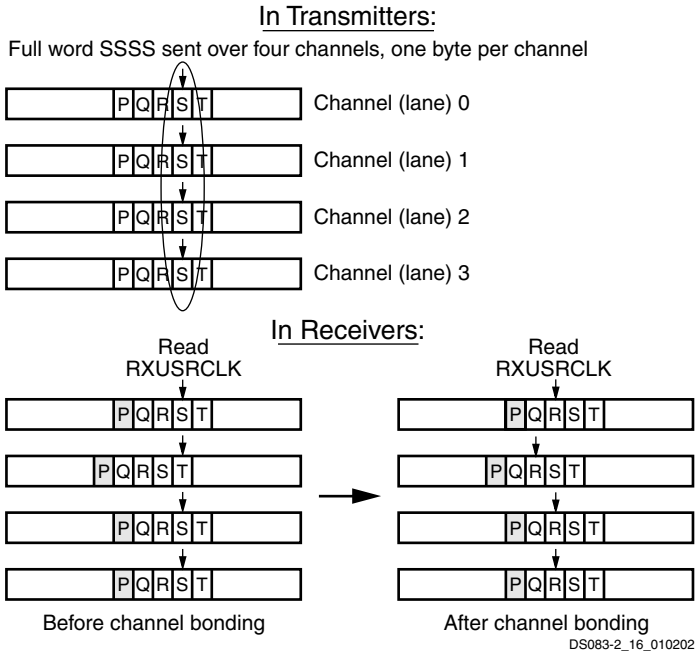

Figure 7: **Channel Bonding (Alignment)**

RocketIO X Configuration

This section outlines functions that can be selected or controlled by configuration. Xilinx implementation software supports the transceiver primitives shown in Table 3.

Table 3: **Supported RocketIO X Transceiver Primitives**

Primitive	Description
GT10_CUSTOM	Fully customizable by user
GT10_OC48_1	SONET OC-48, 1-byte data path
GT10_OC48_2	SONET OC-48, 2-byte data path
GT10_OC48_4	SONET OC-48, 4-byte data path
GT10_PCI_EXPRESS_1	PCI Express, 1-byte data path
GT10_PCI_EXPRESS_2	PCI Express, 2-byte data path
GT10_PCI_EXPRESS_4	PCI Express, 4-byte data path
GT10_INFINIBAND_1	Infiniband, 1-byte data path
GT10_INFINIBAND_2	Infiniband, 2-byte data path
GT10_INFINIBAND_4	Infiniband, 4-byte data path

- Execution unit
- Timers
- Debug logic unit

It operates on instructions in a five stage pipeline consisting of a fetch, decode, execute, write-back, and load write-back stage. Most instructions execute in a single cycle, including loads and stores.

Instruction and Data Cache

The embedded PPC405 core provides an instruction cache unit (ICU) and a data cache unit (DCU) that allow concurrent accesses and minimize pipeline stalls. The instruction and data cache array are 16 KB each. Both cache units are two-way set associative. Each way is organized into 256 lines of 32 bytes (eight words). The instruction set provides a rich assortment of cache control instructions, including instructions to read tag information and data arrays.

The PPC405 core accesses external memory through the instruction (ICU) and data cache units (DCU). The cache units each include a 64-bit PLB master interface, cache arrays, and a cache controller. The ICU and DCU handle cache misses as requests over the PLB to another PLB device such as an external bus interface unit. Cache hits are handled as single cycle memory accesses to the instruction and data caches.

Instruction Cache Unit (ICU)

The ICU provides one or two instructions per cycle to the instruction queue over a 64-bit bus. A line buffer (built into the output of the array for manufacturing test) enables the ICU to be accessed only once for every four instructions, to reduce power consumption by the array.

The ICU can forward any or all of the four or eight words of a line fill to the EXU to minimize pipeline stalls caused by cache misses. The ICU aborts speculative fetches abandoned by the EXU, eliminating unnecessary line fills and enabling the ICU to handle the next EXU fetch. Aborting abandoned requests also eliminates unnecessary external bus activity, thereby increasing external bus utilization.

Data Cache Unit (DCU)

The DCU transfers one, two, three, four, or eight bytes per cycle, depending on the number of byte enables presented by the CPU. The DCU contains a single-element command and store data queue to reduce pipeline stalls; this queue enables the DCU to independently process load/store and cache control instructions. Dynamic PLB request prioritization reduces pipeline stalls even further. When the DCU is busy with a low-priority request while a subsequent storage operation requested by the CPU is stalled; the DCU automatically increases the priority of the current request to the PLB.

The DCU provides additional features that allow the programmer to tailor its performance for a given application. The DCU can function in write-back or write-through mode, as controlled by the Data Cache Write-through Register (DCWR) or the Translation Look-aside Buffer (TLB); the cache controller can be tuned for a balance of performance and memory coherency. Write-on-allocate, controlled by the store word on allocate (SWOA) field of the Core Configuration Register 0 (CCR0), can inhibit line fills caused by store misses, to further reduce potential pipeline stalls and unwanted external bus traffic.

Fetch and Decode Logic

The fetch/decode logic maintains a steady flow of instructions to the execution unit by placing up to two instructions in the fetch queue. The fetch queue consists of three buffers: pre-fetch buffer 1 (PFB1), pre-fetch buffer 0 (PFB0), and decode (DCD). The fetch logic ensures that instructions proceed directly to decode when the queue is empty.

Static branch prediction as implemented on the PPC405 core takes advantage of some standard statistical properties of code. Branches with negative address displacement are by default assumed taken. Branches that do not test the condition or count registers are also predicted as taken. The PPC405 core bases branch prediction upon these default conditions when a branch is not resolved and speculatively fetches along the predicted path. The default prediction can be overridden by software at assembly or compile time.

Branches are examined in the decode and pre-fetch buffer 0 fetch queue stages. Two branch instructions can be handled simultaneously. If the branch in decode is not taken, the fetch logic fetches along the predicted path of the branch instruction in pre-fetch buffer 0. If the branch in decode is taken, the fetch logic ignores the branch instruction in pre-fetch buffer 0.

Execution Unit

The embedded PPC405 core has a single issue execution unit (EXU) containing the register file, arithmetic logic unit (ALU), and the multiply-accumulate (MAC) unit. The execution unit performs all 32-bit PowerPC integer instructions in hardware.

The register file is comprised of thirty-two 32-bit general purpose registers (GPR), which are accessed with three read ports and two write ports. During the decode stage, data is read out of the GPRs and fed to the execution unit. Likewise, during the write-back stage, results are written to the GPR. The use of the five ports on the register file enables either a load or a store operation to execute in parallel with an ALU operation.

Memory Management Unit (MMU)

The embedded PPC405 core has a 4 GB address space, which is presented as a flat address space.

The MMU provides address translation, protection functions, and storage attribute control for embedded applications. The MMU supports demand-paged virtual memory and other management schemes that require precise control of logical-to-physical address mapping and flexible

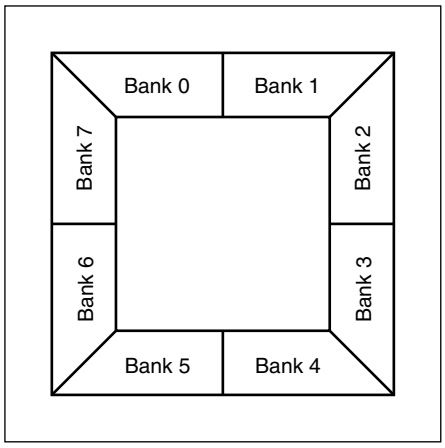

Figure 24: **I/O Banks: Wire-Bond Packages (FG) Top View**

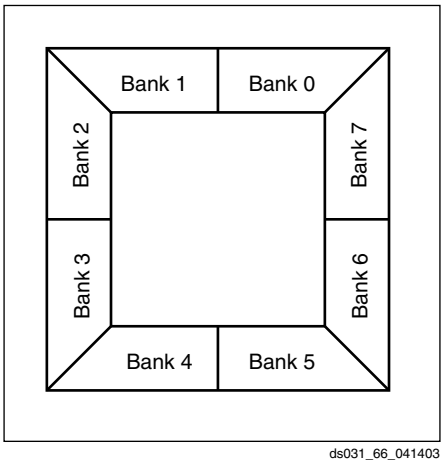

Figure 25: **I/O Banks: Flip-Chip Packages (FF) Top View**

Some input standards require a user-supplied threshold voltage (V_{REF}), and certain user-I/O pins are automatically configured as V_{REF} inputs. Approximately one in six of the I/O pins in the bank assume this role.

V_{REF} pins within a bank are interconnected internally, thus only one V_{REF} voltage can be used within each bank. However, for correct operation, all V_{REF} pins in the bank must be connected to the external reference voltage source.

The V_{CCO} and the V_{REF} pins for each bank appear in the device pinout tables. Within a given package, the number of V_{REF} and V_{CCO} pins can vary depending on the size of device. In larger devices, more I/O pins convert to V_{REF} pins. Since these are always a superset of the V_{REF} pins used for smaller devices, it is possible to design a PCB that permits migration to a larger device if necessary.

All V_{REF} pins for the largest device anticipated must be connected to the V_{REF} voltage and not used for I/O. In smaller devices, some V_{CCO} pins used in larger devices do not connect within the package. These unconnected pins can be left unconnected externally, or, if necessary, they can be connected to V_{CCO} to permit migration to a larger device.

Rules for Combining I/O Standards in the Same Bank

The following rules must be obeyed to combine different input, output, and bi-directional standards in the same bank:

1. **Combining output standards only.** Output standards with the same output V_{CCO} requirement can be combined in the same bank.
   Compatible example:
   SSTL2_I and LVDS_25 outputs
   Incompatible example:
   SSTL2_I (output V_{CCO} = 2.5V) and
   LVCMOS33 (output V_{CCO} = 3.3V) outputs
2. **Combining input standards only.** Input standards with the same input V_{CCO} and input V_{REF} requirements can be combined in the same bank.
   Compatible example:
   LVCMOS15 and HSTL_IV inputs
   Incompatible example:
   LVCMOS15 (input V_{CCO} = 1.5V) and
   LVCMOS18 (input V_{CCO} = 1.8V) inputs
   Incompatible example:
   HSTL_I_DCI_18 (V_{REF} = 0.9V) and
   HSTL_IV_DCI_18 (V_{REF} = 1.1V) inputs
3. **Combining input standards and output standards.** Input standards and output standards with the same input V_{CCO} and output V_{CCO} requirement can be combined in the same bank.
   Compatible example:
   LVDS_25 output and HSTL_I input
   Incompatible example:
   LVDS_25 output (output V_{CCO} = 2.5V) and
   HSTL_I_DCI_18 input (input V_{CCO} = 1.8V)
4. **Combining bi-directional standards with input or output standards.** When combining bi-directional I/O with other standards, make sure the bi-directional standard can meet rules 1 through 3 above.
5. **Additional rules for combining DCI I/O standards.**
   a. No more than one Single Termination type (input or output) is allowed in the same bank.
      Incompatible example:
      HSTL_IV_DCI input and HSTL_III_DCI input
   b. No more than one Split Termination type (input or output) is allowed in the same bank.
      Incompatible example:
      HSTL_I_DCI input and HSTL_II_DCI input

The implementation tools will enforce the above design rules.

Table 12, page 30, summarizes all standards and voltage supplies.

Table 2: **Recommended Operating Conditions**

Symbol	Description	Grade	Virtex-II Pro X		Virtex-II Pro		Units
			Min	Max	Min	Max	
V_{CCINT}	Internal supply voltage relative to GND, T_J = 0 °C to +85°C	Comm.	1.425	1.575	1.425	1.575	V
	Internal supply voltage relative to GND, T_J = –40°C to +100°C	Indus.	1.425	1.575	1.425	1.575	V
V_{CCAUX}(1)	Auxiliary supply voltage relative to GND, T_J = 0 °C to +85°C	Comm.	2.375	2.625	2.375	2.625	V
	Auxiliary supply voltage relative to GND, T_J = –40°C to +100°C	Indus.	2.375	2.625	2.375	2.625	V
V_{CCO}(2,3)	Supply voltage relative to GND, T_J = 0 °C to +85°C	Comm.	1.2	3.45(5)	1.2	3.45(5)	V
	Supply voltage relative to GND, T_J = –40°C to +100°C	Indus.	1.2	3.45(5)	1.2	3.45(5)	V
V_{IN}	3.3V supply voltage relative to GND, T_J = 0 °C to +85°C	Comm.	GND – 0.2	3.45(5)	GND – 0.2	3.45(5)	V
	3.3V supply voltage relative to GND, T_J = –40°C to +100°C	Indus.	GND – 0.2	3.45(5)	GND – 0.2	3.45(5)	V
	2.5V and below supply voltage relative to GND, T_J = 0 °C to +85°C	Comm.	GND – 0.2	V_{CCO} + 0.2	GND – 0.2	V_{CCO} + 0.2	V
	2.5V and below supply voltage relative to GND, T_J = –40°C to +100°C	Indus.	GND – 0.2	V_{CCO} + 0.2	GND – 0.2	V_{CCO} + 0.2	V
V_{BATT}(4)	Battery voltage relative to GND, T_J = 0 °C to +85°C	Comm.	1.0	3.6	1.0	3.6	V
	Battery voltage relative to GND, T_J = –40°C to +100°C	Indus.	1.0	3.6	1.0	3.6	V
AVCCAUXRX(6)	Auxilliary receive supply voltage relative to GNDA	Comm.	1.425(7)	1.575(7)	2.375	2.625	V
		Indus.	1.425(7)	1.575(7)	2.375	2.625	V
AVCCAUXTX(6)	Auxilliary transmit supply voltage relative to GNDA	Comm.	2.375	2.625	2.375	2.625	V
		Indus.	2.375	2.625	2.375	2.625	V
V_{TRX}	Terminal receive supply voltage relative to GND	Comm.	0	2.625	1.6	2.625	V
		Indus.	0	2.625	1.6	2.625	V
V_{TTX}	Terminal transmit supply voltage relative to GND	Comm.	1.425	1.575	1.6	2.625	V
		Indus.	1.425	1.575	1.6	2.625	V

Notes:
1. Recommended maximum voltage droop for V_{CCAUX} is 10 mV/ms.
2. Configuration data is retained even if V_{CCO} drops to 0V.
3. For 3.3V I/O operation, refer to **XAPP659**, available on the Xilinx website at **www.xilinx.com**.
4. If battery is not used, connect V_{BATT} to GND or V_{CCAUX}.
5. For PCI and PCI-X, refer to **XAPP653**, available on the Xilinx website at **www.xilinx.com**.
6. **IMPORTANT!** The RocketIO transceivers have certain power guidelines that must be met, even if unused in the design. Please refer to the section entitled “Powering the RocketIO Transceivers” in the ***RocketIO Transceiver User Guide*** or ***RocketIO X Transceiver User Guide*** for more details.
7. For non-8B/10B-encoded data, the specification for AVCCAUXRX is 1.8V ±5% (1.71 – 1.89V).

Table 14 shows internal (register-to-register) performance. Values are reported in MHz.

Table 14: **Register-to-Register Performance**

Description	Device Used & Speed Grade	Register-to-Register Performance	Units
Basic Functions:			
16-bit Address Decoder	XC2VP20FF1152-6	547	MHz
32-bit Address Decoder	XC2VP20FF1152-6	392	MHz
64-bit Address Decoder	XC2VP20FF1152-6	310	MHz
4:1 MUX	XC2VP20FF1152-6	710	MHz
8:1 MUX	XC2VP20FF1152-6	609	MHz
16:1 MUX	XC2VP20FF1152-6	472	MHz
32:1 MUX	XC2VP20FF1152-6	400	MHz
Register to LUT to Register	XC2VP20FF1152-6	1046	MHz
8-bit Adder	XC2VP20FF1152-6	337	MHz
16-bit Adder	XC2VP20FF1152-6	334	MHz
32-bit Adder	XC2VP20FF1152-6	252	MHz
64-bit Adder	XC2VP20FF1152-6	202	MHz
128-bit Adder	XC2VP20FF1152-6	131	MHz
24-bit Counter	XC2VP20FF1152-6	309	MHz
64-bit Counter	XC2VP20FF1152-6	207	MHz
64-bit Accumulator	XC2VP20FF1152-6	150	MHz
Multiplier 18x18 (with Block RAM inputs)	XC2VP20FF1152-6	135	MHz
Multiplier 18x18 (with Register inputs)	XC2VP20FF1152-6	147	MHz
Memory:			
Block RAM			
Single-Port 4096 x 4 bits	XC2VP20FF1152-6	355	MHz
Distributed RAM			
Single-Port 16 x 8-bit	XC2VP20FF1152-6	555	MHz
Single-Port 32 x 8-bit	XC2VP20FF1152-6	557	MHz
Single-Port 64 x 8-bit	XC2VP20FF1152-6	408	MHz
Single-Port 128 x 8-bit	XC2VP20FF1152-6	336	MHz
Dual-Port 16 x 8-bit	XC2VP20FF1152-6	549	MHz
Dual-Port 32 x 8-bit	XC2VP20FF1152-6	460	MHz
Dual-Port 64 x 8-bit	XC2VP20FF1152-6	407	MHz

FG676/FGG676 Fine-Pitch BGA Package

As shown in Table 7, XC2VP20, XC2VP30, and XC2VP40 Virtex-II Pro devices are available in the FG676/FGG676 fine-pitch BGA package. The pins in these devices are the same, except for the differences shown in the "No Connects" column. Following this table are the FG676/FGG676 Fine-Pitch BGA Package Specifications (1.00mm pitch).

Table 7: **FG676/FGG676 — XC2VP20, XC2VP30, and XC2VP40**

Bank	Pin Description	Pin Number	No Connects		
			XC2VP20	XC2VP30	XC2VP40
0	IO_L01N_0/VRP_0	E5			
0	IO_L01P_0/VRN_0	D5			
0	IO_L02N_0	E6			
0	IO_L02P_0	D6			
0	IO_L03N_0	G7			
0	IO_L03P_0/VREF_0	F7			
0	IO_L05_0/No_Pair	E7			
0	IO_L06N_0	D7			
0	IO_L06P_0	C7			
0	IO_L07N_0	H8			
0	IO_L07P_0	G8			
0	IO_L09N_0	F8			
0	IO_L09P_0/VREF_0	E8			
0	IO_L37N_0	B8			
0	IO_L37P_0	A8			
0	IO_L39N_0	H9			
0	IO_L39P_0	G9			
0	IO_L43N_0	F9			
0	IO_L43P_0	E9			
0	IO_L45N_0	D9			
0	IO_L45P_0/VREF_0	C9			
0	IO_L46N_0	H10			
0	IO_L46P_0	H11			
0	IO_L48N_0	E10			
0	IO_L48P_0	E11			
0	IO_L49N_0	D10			
0	IO_L49P_0	C10			
0	IO_L50_0/No_Pair	G11			
0	IO_L53_0/No_Pair	F11			
0	IO_L54N_0	J12			
0	IO_L54P_0	H12			

Table 7: **FG676/FGG676 — XC2VP20, XC2VP30, and XC2VP40**

Bank	Pin Description	Pin Number	No Connects		
			XC2VP20	XC2VP30	XC2VP40
N/A	GND	R15			
N/A	GND	R16			
N/A	GND	R24			
N/A	GND	T11			
N/A	GND	T12			
N/A	GND	T13			
N/A	GND	T14			
N/A	GND	T15			
N/A	GND	T16			
N/A	GND	U6			
N/A	GND	U21			
N/A	GND	W4			
N/A	GND	W23			
N/A	GND	AA10			
N/A	GND	AA17			
N/A	GND	AC4			
N/A	GND	AC8			
N/A	GND	AC19			
N/A	GND	AC23			
N/A	GND	AD3			
N/A	GND	AD24			
N/A	GND	AE2			
N/A	GND	AE25			
N/A	GND	AF1			
N/A	GND	AF26			

Notes:
1. See Table 4 for an explanation of the signals available on this pin.

Table 8: **FF672 — XC2VP2, XC2VP4, and XC2VP7**

Bank	Pin Description	Pin Number	No Connects		
			XC2VP2	XC2VP4	XC2VP7
6	IO_L52N_6	U22	NC		
6	IO_L53P_6	U23	NC		
6	IO_L53N_6	U24	NC		
6	IO_L54P_6	V26	NC		
6	IO_L54N_6	U26	NC		
6	IO_L55P_6	U20	NC		
6	IO_L55N_6	T19	NC		
6	IO_L56P_6	T20	NC		
6	IO_L56N_6	R20	NC		
6	IO_L57P_6	T21	NC		
6	IO_L57N_6/VREF_6	T22	NC		
6	IO_L58P_6	T23	NC		
6	IO_L58N_6	T24	NC		
6	IO_L59P_6	T25	NC		
6	IO_L59N_6	T26	NC		
6	IO_L60P_6	R19	NC		
6	IO_L60N_6	P19	NC		
6	IO_L85P_6	R21			
6	IO_L85N_6	R22			
6	IO_L86P_6	R23			
6	IO_L86N_6	R24			
6	IO_L87P_6	R25			
6	IO_L87N_6/VREF_6	R26			
6	IO_L88P_6	P20			
6	IO_L88N_6	P21			
6	IO_L89P_6	P22			
6	IO_L89N_6	P23			
6	IO_L90P_6	P24			
6	IO_L90N_6	P25			
7	IO_L90P_7	N25			
7	IO_L90N_7	N24			
7	IO_L89P_7	N23			
7	IO_L89N_7	N22			
7	IO_L88P_7	N21			
7	IO_L88N_7/VREF_7	N20			
7	IO_L87P_7	M26			

Table 8: **FF672 — XC2VP2, XC2VP4, and XC2VP7**

Bank	Pin Description	Pin Number	No Connects		
			XC2VP2	XC2VP4	XC2VP7
N/A	GND	R15			
N/A	GND	R16			
N/A	GND	R17			
N/A	GND	T11			
N/A	GND	T12			
N/A	GND	T13			
N/A	GND	T14			
N/A	GND	T15			
N/A	GND	T16			
N/A	GND	U10			
N/A	GND	U12			
N/A	GND	U13			
N/A	GND	U14			
N/A	GND	U15			
N/A	GND	U17			
N/A	GND	Y20			
N/A	GND	AA21			
N/A	GND	AB22			
N/A	GND	AC23			
N/A	GND	AD24			

Notes:
1. See Table 4 for an explanation of the signals available on this pin.

Table 10: **FF1152 — XC2VP20, XC2VP30, XC2VP40, and XC2VP50**

Bank	Pin Description	Pin Number	No Connects			
			XC2VP20	XC2VP30	XC2VP40	XC2VP50
0	IO_L43P_0	E22				
0	IO_L44N_0	E25				
0	IO_L44P_0	D25				
0	IO_L45N_0	H21				
0	IO_L45P_0/VREF_0	G21				
0	IO_L46N_0	D22				
0	IO_L46P_0	D23				
0	IO_L47N_0	D24				
0	IO_L47P_0	C24				
0	IO_L48N_0	K20				
0	IO_L48P_0	J20				
0	IO_L49N_0	F21				
0	IO_L49P_0	E21				
0	IO_L50_0/No_Pair	C21				
0	IO_L53_0/No_Pair	C22				
0	IO_L54N_0	L19				
0	IO_L54P_0	K19				
0	IO_L55N_0	G20				
0	IO_L55P_0	F20				
0	IO_L56N_0	D21				
0	IO_L56P_0	D20				
0	IO_L57N_0	J19				
0	IO_L57P_0/VREF_0	H19				
0	IO_L67N_0	G19				
0	IO_L67P_0	F19				
0	IO_L68N_0	E19				
0	IO_L68P_0	D19				
0	IO_L69N_0	L18				
0	IO_L69P_0/VREF_0	K18				
0	IO_L73N_0	G18				
0	IO_L73P_0	F18				
0	IO_L74N_0/GCLK7P	E18				
0	IO_L74P_0/GCLK6S	D18				
0	IO_L75N_0/GCLK5P	J18				
0	IO_L75P_0/GCLK4S	H18				
1	IO_L75N_1/GCLK3P	H17				
1	IO_L75P_1/GCLK2S	J17				

Table 10: **FF1152 — XC2VP20, XC2VP30, XC2VP40, and XC2VP50**

Bank	Pin Description	Pin Number	No Connects			
			XC2VP20	XC2VP30	XC2VP40	XC2VP50
2	IO_L57N_2	R4				
2	IO_L57P_2	R3				
2	IO_L58N_2/VREF_2	R2				
2	IO_L58P_2	T2				
2	IO_L59N_2	T8				
2	IO_L59P_2	T7				
2	IO_L60N_2	T6				
2	IO_L60P_2	T5				
2	IO_L85N_2	T4				
2	IO_L85P_2	T3				
2	IO_L86N_2	U10				
2	IO_L86P_2	U9				
2	IO_L87N_2	U6				
2	IO_L87P_2	U5				
2	IO_L88N_2/VREF_2	U2				
2	IO_L88P_2	V2				
2	IO_L89N_2	U8				
2	IO_L89P_2	U7				
2	IO_L90N_2	U4				
2	IO_L90P_2	U3				
3	IO_L90N_3	V3				
3	IO_L90P_3	V4				
3	IO_L89N_3	V7				
3	IO_L89P_3	V8				
3	IO_L88N_3	V5				
3	IO_L88P_3	V6				
3	IO_L87N_3/VREF_3	W2				
3	IO_L87P_3	Y2				
3	IO_L86N_3	V9				
3	IO_L86P_3	V10				
3	IO_L85N_3	W3				
3	IO_L85P_3	W4				
3	IO_L60N_3	Y1				
3	IO_L60P_3	AA1				
3	IO_L59N_3	V11				
3	IO_L59P_3	W11				
3	IO_L58N_3	W5				

Table 10: **FF1152 — XC2VP20, XC2VP30, XC2VP40, and XC2VP50**

Bank	Pin Description	Pin Number	No Connects			
			XC2VP20	XC2VP30	XC2VP40	XC2VP50
6	IO_L34P_6	AE30				
6	IO_L34N_6	AE31				
6	IO_L35P_6	AD27				
6	IO_L35N_6	AD28				
6	IO_L36P_6	AF33				
6	IO_L36N_6	AE33				
6	IO_L37P_6	AD29				
6	IO_L37N_6	AD30				
6	IO_L38P_6	AB25				
6	IO_L38N_6	AB26				
6	IO_L39P_6	AD31				
6	IO_L39N_6/VREF_6	AD32				
6	IO_L40P_6	AC28				
6	IO_L40N_6	AC29				
6	IO_L41P_6	AB27				
6	IO_L41N_6	AB28				
6	IO_L42P_6	AE34				
6	IO_L42N_6	AD34				
6	IO_L43P_6	AC31				
6	IO_L43N_6	AC32				
6	IO_L44P_6	AA25				
6	IO_L44N_6	AA26				
6	IO_L45P_6	AD33				
6	IO_L45N_6/VREF_6	AC33				
6	IO_L46P_6	AB29				
6	IO_L46N_6	AB30				
6	IO_L47P_6	AA27				
6	IO_L47N_6	AA28				
6	IO_L48P_6	AB31				
6	IO_L48N_6	AB32				
6	IO_L49P_6	AA29				
6	IO_L49N_6	AA30				
6	IO_L50P_6	Y25				
6	IO_L50N_6	Y26				
6	IO_L51P_6	AC34				
6	IO_L51N_6/VREF_6	AB34				
6	IO_L52P_6	AA31				
6	IO_L52N_6	AA32				

Table 10: **FF1152 — XC2VP20, XC2VP30, XC2VP40, and XC2VP50**

Bank	Pin Description	Pin Number	No Connects			
			XC2VP20	XC2VP30	XC2VP40	XC2VP50
1	VCCO_1	L15				
1	VCCO_1	M13				
1	VCCO_1	M14				
1	VCCO_1	M15				
1	VCCO_1	M16				
1	VCCO_1	M17				
2	VCCO_2	F3				
2	VCCO_2	K6				
2	VCCO_2	M11				
2	VCCO_2	N11				
2	VCCO_2	N12				
2	VCCO_2	P11				
2	VCCO_2	P12				
2	VCCO_2	R5				
2	VCCO_2	R11				
2	VCCO_2	R12				
2	VCCO_2	T12				
2	VCCO_2	U12				
3	VCCO_3	V12				
3	VCCO_3	W12				
3	VCCO_3	Y5				
3	VCCO_3	Y11				
3	VCCO_3	Y12				
3	VCCO_3	AA11				
3	VCCO_3	AA12				
3	VCCO_3	AB11				
3	VCCO_3	AB12				
3	VCCO_3	AC11				
3	VCCO_3	AE6				
3	VCCO_3	AJ3				
4	VCCO_4	AC13				
4	VCCO_4	AC14				
4	VCCO_4	AC15				
4	VCCO_4	AC16				
4	VCCO_4	AC17				
4	VCCO_4	AD12				
4	VCCO_4	AD13				
4	VCCO_4	AD14				

Table 11: **FF1148 — XC2VP40 and XC2VP50**

Bank	Pin Description	Pin Number	No Connects	
			XC2VP40	XC2VP50
1	IO_L43P_1	B13		
1	IO_L39N_1	G13		
1	IO_L39P_1	F13		
1	IO_L38N_1	J15		
1	IO_L38P_1	J14		
1	IO_L37N_1	B12		
1	IO_L37P_1	A12		
1	IO_L27N_1/VREF_1	D13		
1	IO_L27P_1	D12		
1	IO_L26N_1	L13		
1	IO_L26P_1	K13		
1	IO_L25N_1	F12		
1	IO_L25P_1	E12		
1	IO_L21N_1	B11		
1	IO_L21P_1	A11		
1	IO_L20N_1	K12		
1	IO_L20P_1	J12		
1	IO_L19N_1	C12		
1	IO_L19P_1	C11		
1	IO_L09N_1/VREF_1	F11		
1	IO_L09P_1	E11		
1	IO_L08N_1	H13		
1	IO_L08P_1	H12		
1	IO_L07N_1	G12		
1	IO_L07P_1	G11		
1	IO_L06N_1	B10		
1	IO_L06P_1	A10		
1	IO_L05_1/No_Pair	G10		
1	IO_L03N_1/VREF_1	D10		
1	IO_L03P_1	C10		
1	IO_L02N_1	K11		
1	IO_L02P_1	J11		
1	IO_L01N_1/VRP_1	F10		
1	IO_L01P_1/VRN_1	E10		
2	IO_L01N_2/VRP_2	B8		
2	IO_L01P_2/VRN_2	B9		
2	IO_L02N_2	C9		

Table 11: **FF1148 — XC2VP40 and XC2VP50**

Bank	Pin Description	Pin Number	No Connects	
			XC2VP40	XC2VP50
3	IO_L55N_3	Y1		
3	IO_L55P_3	Y2		
3	IO_L54N_3	AA5		
3	IO_L54P_3	AA6		
3	IO_L53N_3	Y10		
3	IO_L53P_3	Y11		
3	IO_L52N_3	AA4		
3	IO_L52P_3	AB4		
3	IO_L51N_3/VREF_3	AA1		
3	IO_L51P_3	AA2		
3	IO_L50N_3	Y9		
3	IO_L50P_3	AA9		
3	IO_L49N_3	AB6		
3	IO_L49P_3	AB7		
3	IO_L48N_3	AB2		
3	IO_L48P_3	AB3		
3	IO_L47N_3	AA10		
3	IO_L47P_3	AA11		
3	IO_L46N_3	AC5		
3	IO_L46P_3	AC6		
3	IO_L45N_3/VREF_3	AC3		
3	IO_L45P_3	AC4		
3	IO_L44N_3	AA7		
3	IO_L44P_3	AA8		
3	IO_L43N_3	AC1		
3	IO_L43P_3	AC2		
3	IO_L42N_3	AD5		
3	IO_L42P_3	AD6		
3	IO_L41N_3	AB10		
3	IO_L41P_3	AB11		
3	IO_L40N_3	AD3		
3	IO_L40P_3	AE3		
3	IO_L39N_3/VREF_3	AD1		
3	IO_L39P_3	AD2		
3	IO_L38N_3	AB8		
3	IO_L38P_3	AC7		
3	IO_L37N_3	AE5		
3	IO_L37P_3	AE6		

Table 12: **FF1517 — XC2VP50 and XC2VP70**

Bank	Pin Description	Pin Number	No Connects	
			XC2VP50	XC2VP70
1	IO_L64N_1	E18		
1	IO_L64P_1	D18		
1	IO_L60N_1	G18		
1	IO_L60P_1	F18		
1	IO_L59N_1	L18		
1	IO_L59P_1	K18		
1	IO_L58N_1	J18		
1	IO_L58P_1	H18		
1	IO_L57N_1/VREF_1	D17		
1	IO_L57P_1	C17		
1	IO_L56N_1	N18		
1	IO_L56P_1	M18		
1	IO_L55N_1	E17		
1	IO_L55P_1	E16		
1	IO_L54N_1	G17		
1	IO_L54P_1	F16		
1	IO_L53_1/No_Pair	J17		
1	IO_L50_1/No_Pair	H17		
1	IO_L49N_1	J16		
1	IO_L49P_1	H16		
1	IO_L48N_1	D15		
1	IO_L48P_1	C15		
1	IO_L47N_1	L17		
1	IO_L47P_1	K16		
1	IO_L46N_1	F15		
1	IO_L46P_1	E15		
1	IO_L45N_1/VREF_1	H15		
1	IO_L45P_1	G15		
1	IO_L44N_1	N17		
1	IO_L44P_1	M17		
1	IO_L43N_1	D14		
1	IO_L43P_1	C14		
1	IO_L39N_1	F14		
1	IO_L39P_1	E14		
1	IO_L38N_1	M16		
1	IO_L38P_1	M15		
1	IO_L37N_1	H14		
1	IO_L37P_1	G14		

Table 13: **FF1704 — XC2VP70, XC2VPX70, and XC2VP100**

Bank	Pin Description		Pin Number	No Connects	
	Virtex-II Pro Devices	XC2VPX70 (if Different)		XC2VP70, XC2VPX70	XC2VP100
3	IO_L53N_3		AE10		
3	IO_L53P_3		AE11		
3	IO_L52N_3		AE1		
3	IO_L52P_3		AE2		
3	IO_L51N_3/VREF_3		AE4		
3	IO_L51P_3		AE5		
3	IO_L50N_3		AF11		
3	IO_L50P_3		AE12		
3	IO_L49N_3		AE7		
3	IO_L49P_3		AE8		
3	IO_L48N_3		AF1		
3	IO_L48P_3		AF2		
3	IO_L47N_3		AG12		
3	IO_L47P_3		AF12		
3	IO_L46N_3		AF3		
3	IO_L46P_3		AF4		
3	IO_L45N_3/VREF_3		AF5		
3	IO_L45P_3		AF6		
3	IO_L44N_3		AF7		
3	IO_L44P_3		AF8		
3	IO_L43N_3		AF9		
3	IO_L43P_3		AF10		
3	IO_L42N_3		AG2		
3	IO_L42P_3		AG3		
3	IO_L41N_3		AG10		
3	IO_L41P_3		AG11		
3	IO_L40N_3		AG4		
3	IO_L40P_3		AG5		
3	IO_L39N_3/VREF_3		AG6		
3	IO_L39P_3		AG7		
3	IO_L38N_3		AG8		
3	IO_L38P_3		AH8		
3	IO_L37N_3		AH1		
3	IO_L37P_3		AH2		
3	IO_L36N_3		AH3		
3	IO_L36P_3		AJ3		

Table 13: **FF1704 — XC2VP70, XC2VPX70, and XC2VP100**

Bank	Pin Description		Pin Number	No Connects	
	Virtex-II Pro Devices	XC2VPX70 (if Different)		XC2VP70, XC2VPX70	XC2VP100
7	IO_L87P_7		AA33		
7	IO_L87N_7		AA34		
7	IO_L86P_7		Y31		
7	IO_L86N_7		Y32		
7	IO_L85P_7		Y39		
7	IO_L85N_7		Y40		
7	IO_L60P_7		Y36		
7	IO_L60N_7		Y37		
7	IO_L59P_7		Y33		
7	IO_L59N_7		Y34		
7	IO_L58P_7		W41		
7	IO_L58N_7/VREF_7		W42		
7	IO_L57P_7		W39		
7	IO_L57N_7		W40		
7	IO_L56P_7		W31		
7	IO_L56N_7		W32		
7	IO_L55P_7		W37		
7	IO_L55N_7		W38		
7	IO_L54P_7		W35		
7	IO_L54N_7		W36		
7	IO_L53P_7		W33		
7	IO_L53N_7		W34		
7	IO_L52P_7		V41		
7	IO_L52N_7/VREF_7		V42		
7	IO_L51P_7		V38		
7	IO_L51N_7		V39		
7	IO_L50P_7		V31		
7	IO_L50N_7		U32		
7	IO_L49P_7		V35		
7	IO_L49N_7		V36		
7	IO_L48P_7		V32		
7	IO_L48N_7		V33		
7	IO_L47P_7		U31		
7	IO_L47N_7		T31		
7	IO_L46P_7		U41		
7	IO_L46N_7/VREF_7		U42		

Table 13: **FF1704 — XC2VP70, XC2VPX70, and XC2VP100**

Bank	Pin Description		Pin Number	No Connects	
	Virtex-II Pro Devices	XC2VPX70 (if Different)		XC2VP70, XC2VPX70	XC2VP100
N/A	GND		AA5		
N/A	GND		Y41		
N/A	GND		Y26		
N/A	GND		Y25		
N/A	GND		Y24		
N/A	GND		Y23		
N/A	GND		Y22		
N/A	GND		Y21		
N/A	GND		Y20		
N/A	GND		Y19		
N/A	GND		Y18		
N/A	GND		Y17		
N/A	GND		Y2		
N/A	GND		W26		
N/A	GND		W25		
N/A	GND		W24		
N/A	GND		W23		
N/A	GND		W22		
N/A	GND		W21		
N/A	GND		W20		
N/A	GND		W19		
N/A	GND		W18		
N/A	GND		W17		
N/A	GND		V37		
N/A	GND		V34		
N/A	GND		V26		
N/A	GND		V25		
N/A	GND		V24		
N/A	GND		V23		
N/A	GND		V22		
N/A	GND		V21		
N/A	GND		V20		
N/A	GND		V19		
N/A	GND		V18		
N/A	GND		V17		
N/A	GND		V9		

Table 14: **FF1696 — XC2VP100**

Bank	Pin Description	Pin Number	No Connects
			XC2VP100
6	IO_L62N_6	AL35	
6	IO_L63P_6	AV36	
6	IO_L63N_6/VREF_6	AU36	
6	IO_L64P_6	AV35	
6	IO_L64N_6	AU35	
6	IO_L65P_6	AK35	
6	IO_L65N_6	AJ34	
6	IO_L66P_6	AU41	
6	IO_L66N_6	AU42	
6	IO_L67P_6	AU38	
6	IO_L67N_6	AT38	
6	IO_L68P_6	AK32	
6	IO_L68N_6	AK33	
6	IO_L69P_6	AU37	
6	IO_L69N_6/VREF_6	AT37	
6	IO_L70P_6	AT41	
6	IO_L70N_6	AT42	
6	IO_L71P_6	AK31	
6	IO_L71N_6	AJ31	
6	IO_L72P_6	AT39	
6	IO_L72N_6	AT40	
6	IO_L07P_6	AT35	
6	IO_L07N_6	AT36	
6	IO_L08P_6	AJ32	
6	IO_L08N_6	AJ33	
6	IO_L09P_6	AR42	
6	IO_L09N_6/VREF_6	AP41	
6	IO_L10P_6	AR40	
6	IO_L10N_6	AR41	
6	IO_L11P_6	AH34	
6	IO_L11N_6	AH35	
6	IO_L12P_6	AR38	
6	IO_L12N_6	AR39	
6	IO_L13P_6	AR36	
6	IO_L13N_6	AR37	
6	IO_L14P_6	AH32	
6	IO_L14N_6	AH33	